L Number	Hits	Search Text	DB	Time stamp
1	2	5291061.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:00
2	1		USPAT	2004/09/29 22:59
3	1		USPAT	2004/09/29 22:59
4	1		USPAT	2004/09/29 22:59
5	1		USPAT	2004/09/29 23:00
6	1		USPAT	2004/09/29 23:00
7	2	5323060.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:01
8	2	5502289.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:02
9	2	5721452.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:03
10	1		USPAT	2004/09/29 23:03
11	1		USPAT	2004/09/29 23:03
12	1		USPAT	2004/09/29 23:03
13	2	5815372.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:04
14	2	5886412.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:05
15	2	5963794.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:06
16	2	6005778.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:34
17	1		USPAT	2004/09/29 23:06
18	1		USPAT	2004/09/29 23:06
19	1		USPAT	2004/09/29 23:06
20	1		USPAT	2004/09/29 23:07
21	1		USPAT	2004/09/29 23:07
22	1		USPAT	2004/09/29 23:07

23	1		USPAT	2004/09/29 23:07
24	1		USPAT	2004/09/29 23:07
25	1		USPAT	2004/09/29 23:07
26	1		USPAT	2004/09/29 23:08
27	1		USPAT	2004/09/29 23:08
28	3671212	(substrate carrier board pcb cb (printed adj4 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:34
29	2598502	semiconductor die chip dice ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:35
30	197831	(semiconductor die chip dice ic (integrated adj circuit)) with (stack stacking stacked level multiple)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:36
31	149888	(semiconductor die chip dice ic (integrated adj circuit)) with (stack stacking stacked level)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:38
32	38688	(semiconductor die chip dice ic (integrated adj circuit)) with (stack stacking stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:39
33	18244	((substrate carrier board pcb cb (printed adj4 board))) same ((semiconductor die chip dice ic (integrated adj circuit)) with (stack stacking stacked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:39
34	1113	(((substrate carrier board pcb cb (printed adj4 board))) same ((semiconductor die chip dice ic (integrated adj circuit)) with (stack stacking stacked))) same (adhesive adhesion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/29 23:41

C:\APPS\EAST\Workspaces\10384744.wsp